Title (en)

METHODS OF MANUFACTURING PRINTED CIRCUIT BOARDS USING PARALLEL PROCESSES TO INTERCONNECT WITH SUBASSEMBLIES

Title (de)

VERFAHREN ZUR HERSTELLUNG VON LEITERPLATTEN MIT PARALLELVERFAHREN ZUR VERBINDUNG MIT BAUGRUPPEN

Title (fr)

PROCÉDÉS DE FABRICATION DE CARTES DE CIRCUIT IMPRIMÉ UTILISANT DES PROCESSUS PARALLÈLES EN VUE D'OBTENIR UNE INTERCONNEXION AVEC DES SOUS-ENSEMBLES

Publication

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Application

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Priority

US 2010033295 W 20100430

Abstract (en)

[origin: WO2011136817A1] Methods of manufacturing printed circuit boards using parallel processes to interconnect with subassemblies are provided. In one embodiment, the invention relates to a method of manufacturing a printed circuit board including providing a core subassembly including at least one metal layer, providing a plurality of one-metal layer carriers after parallel processing each of the plurality of one-metal layer carriers, and attaching at least two of the plurality of one-metal layer carriers with each other and with the core subassembly.

IPC 8 full level

H05K 3/46 (2006.01)

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Citation (search report)

- [XY] JP 2004327510 A 20041118 - MATSUSHITA ELECTRIC WORKS LTD
- [Y] US 2010018758 A1 20100128 - YOSHIMURA HIDEAKI [JP], et al
- [Y] US 2008016685 A1 20080124 - OHARA TOSHIHIKO [JP], et al
- [Y] US 2002117743 A1 20020829 - NAKATANI SEIICHI [JP], et al
- See references of WO 2011136817A1

Cited by

US12052824B2

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DOCDB simple family (application)

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